

# N-Channel Enhancement Mode MOSFET

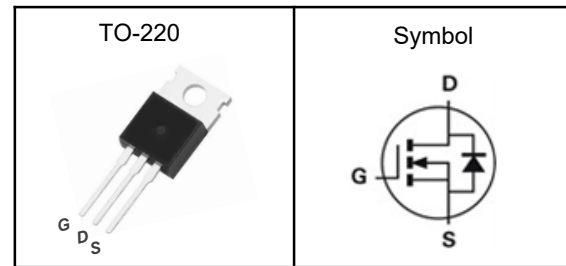
## Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

## Applications

- Power Management in Desktop Computer
- DC/DC Converters

## Pin Description



$V_{DSS}$	150	V
$R_{DS(ON)-Typ}$	3.9	m $\Omega$
$I_D$	190	A

## Absolute Maximum Ratings ( $T_J=25^\circ\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-Source Voltage	150	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$T_J$	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$E_{AS}$	Single Pulse Avalanche Energy	1600	mJ
$I_{DM}^{①}$	Pulse Drain Current Tested	760	A
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$	A
	Continuous Drain Current	$T_C=100^\circ\text{C}$	A
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	W

## Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.35	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature  $150^\circ\text{C}$ .

Note ③ : Surface Mounted on  $1\text{in}^2$  FR-4 board with 1oz.



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**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	150	---	---	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=150V, V_{GS}=0V$	---	---	1	$\mu A$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	---	4.0	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=10V, I_D=40A$	---	3.9	4.5	m $\Omega$
<b>Dynamic Characteristics<sup>⑤</sup></b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=75V, \text{Freq.}=1.0\text{MHz}$	---	10780	---	pF
$C_{oss}$	Output Capacitance		---	10	---	
$C_{rss}$	Reverse Transfer Capacitance		---	840	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DD}=75V, I_D=40A, R_G=3\Omega$	---	38.6	---	nS
$T_r$	Turn-on Rise Time		---	18	---	
$T_{d(off)}$	Turn-off Delay Time		---	70	---	
$T_f$	Turn-off Fall Time		---	21	---	
$Q_g$	Total Gate Charge	$V_{GS}=10V, V_{DD}=75V, I_D=40A$	---	141	---	nC
$Q_{gs}$	Gate-Source Charge		---	41	---	
$Q_{gd}$	Gate-Drain Charge		---	30	---	
<b>Source-Drain Characteristics</b>						
$I_S$	Continuous Source Current		--	---	150	A
$V_{SD}$	Diode Forward Voltage	$I_S=80A, V_{GS}=0V$	---	---	1.2	V

Note ④: Pulse test (pulse width $\leq$ 300 $\mu$ s, duty cycle $\leq$ 2%).

Note ⑤: Guaranteed by design, not subject to production testing.



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Typical Characteristics

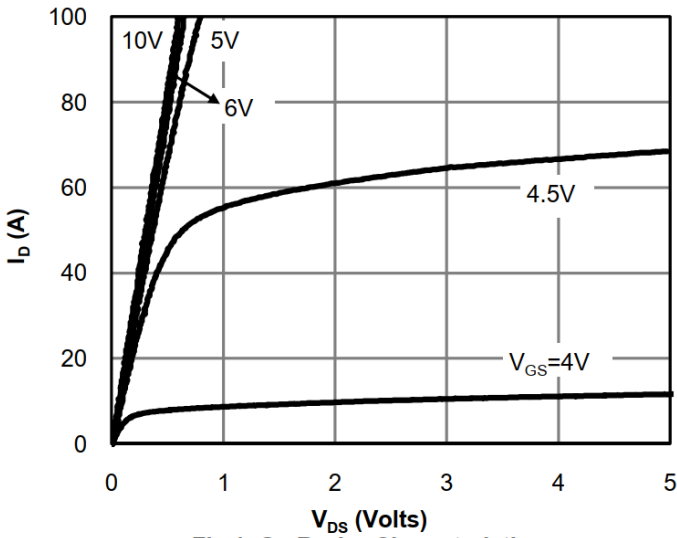


Fig 1: On-Region Characteristics

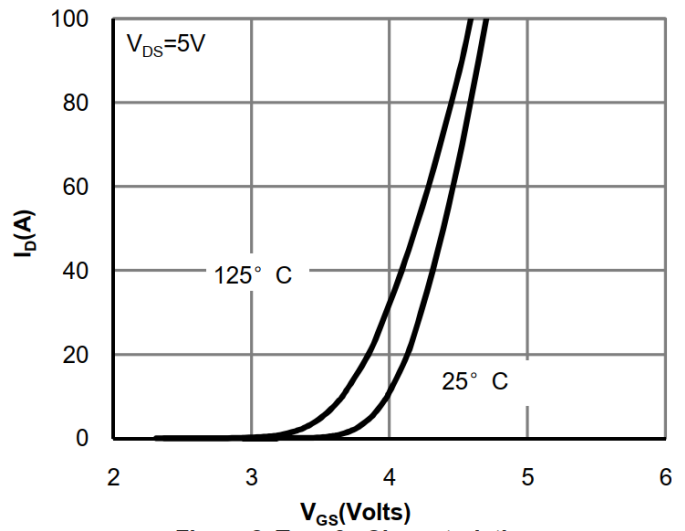


Figure 2: Transfer Characteristics

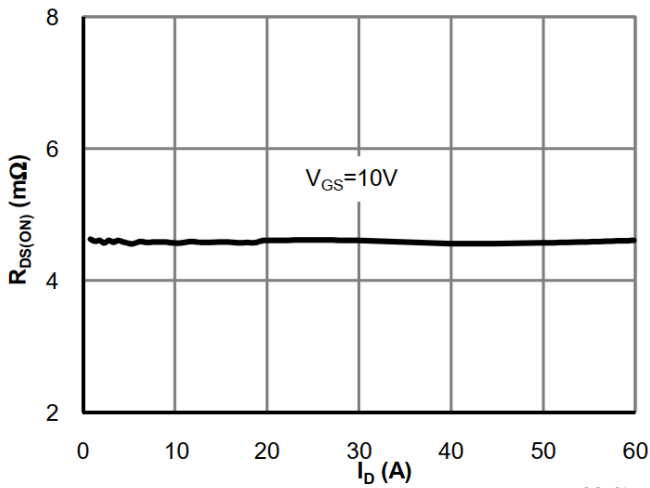


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

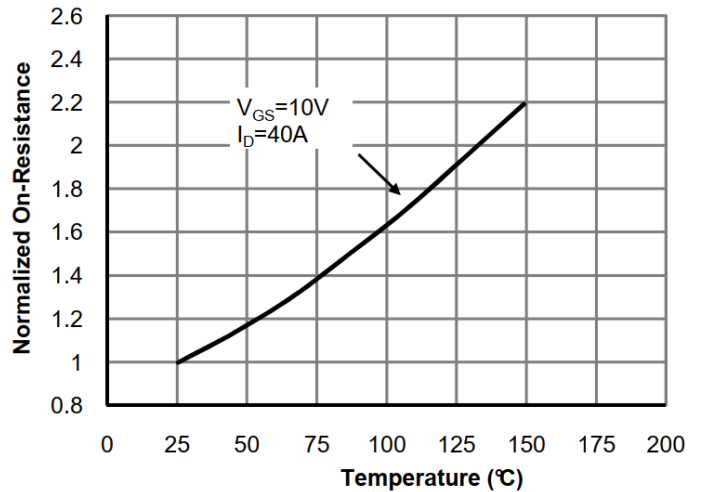


Figure 4: On-Resistance vs. Junction Temperature

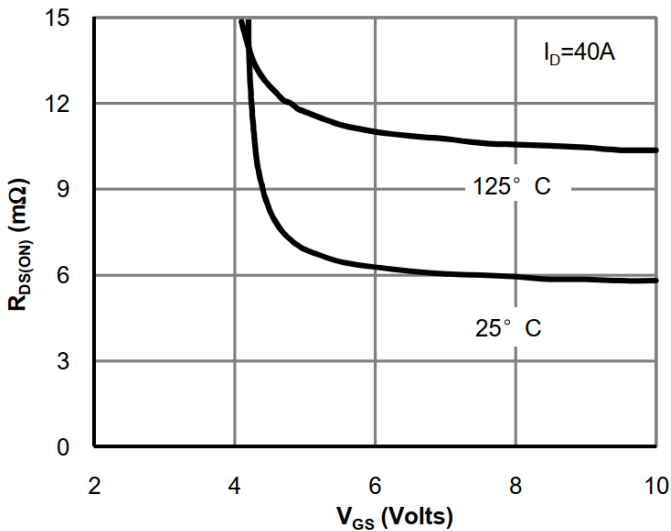


Figure 5: On-Resistance vs. Gate-Source Voltage

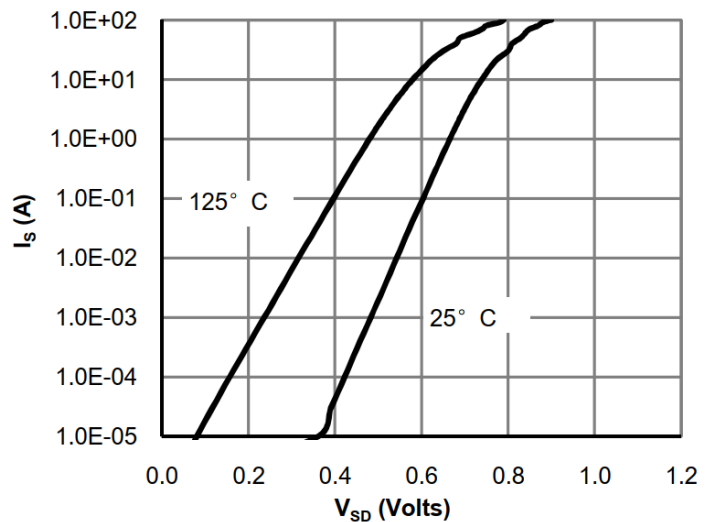


Figure 6: Body-Diode Characteristics

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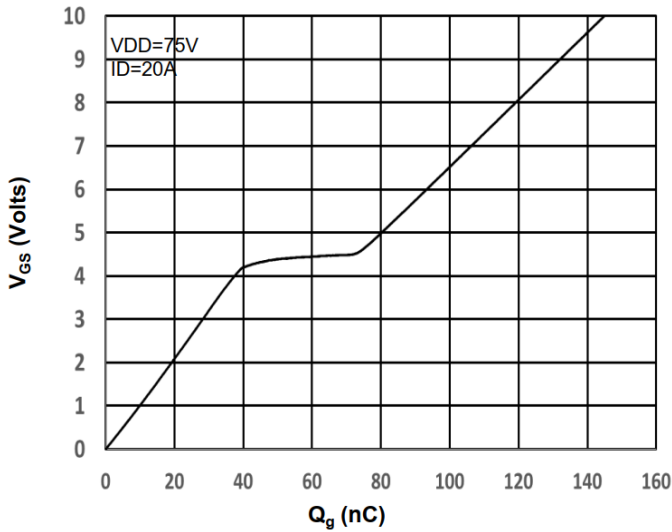


Figure 7: Gate-Charge Characteristics

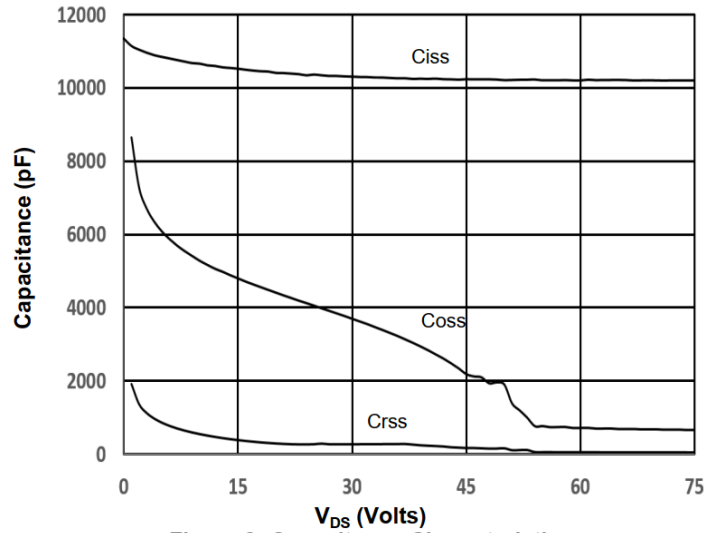


Figure 8: Capacitance Characteristics

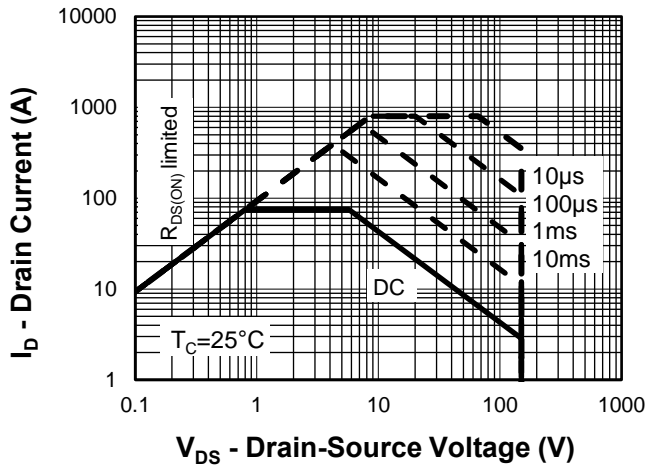


Figure 9. Safe Operation Area

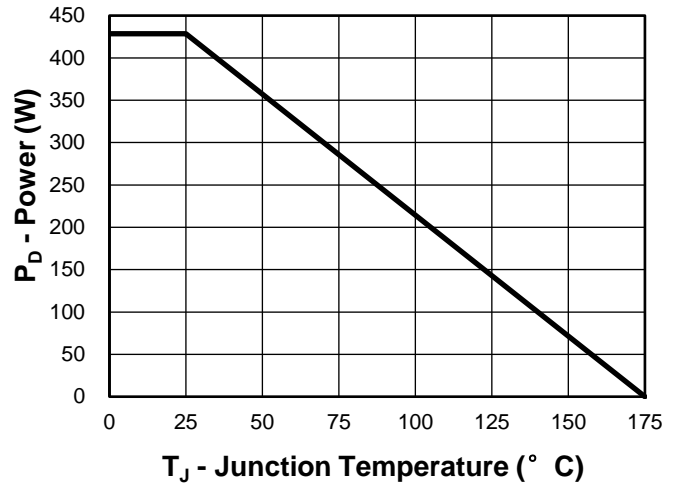
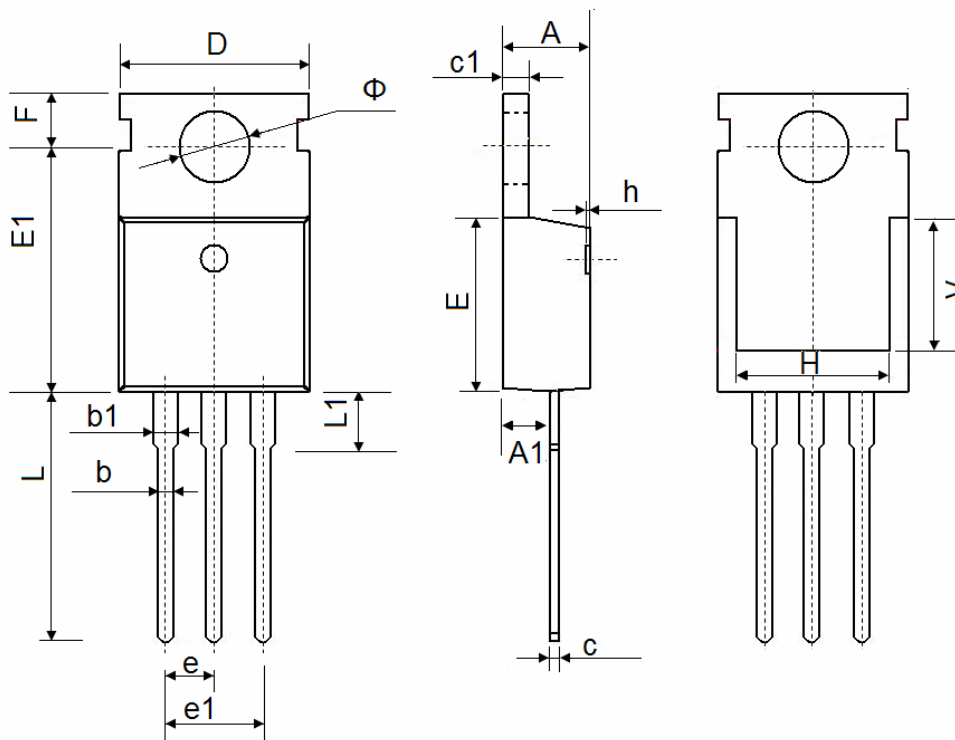


Figure 10. Power Dissipation

**N-Channel Enhancement Mode MOSFET**
**TO-220 Package Outline Data**


Symbol	Dimensions In Millimeters	
	Min.	Max.
A	4.350	4.650
A1	2.250	2.550
b	0.710	0.910
b1	1.170	1.400
c	0.330	0.650
c1	1.200	1.400
D	9.910	10.250
E	8.9500	9.750
E1	12.650	12.950
e	2.540 TYP.	
e1	4.980	5.180
F	2.650	2.950
H	7.900	8.100
h	0.000	0.300
L	12.700	13.500
L1	2.850	3.250
V	7.500 REF.	
$\Phi$	3.400	3.800